PATENT ASSIGNMENT

Electronic Version v1.1
Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Kyosuke Yoshida	08/29/2012
Yoshihiro Tamura	08/31/2012
Ichiro Ogata	10/30/2012
Yoshinori Takagi	09/03/2012
Hirofumi Hibi	09/03/2012
Daisuke Izaki	09/06/2012

RECEIVING PARTY DATA

Name:	Sony Corporation
Street Address:	1-7-1 Konan, Minato-ku
City:	Tokyo
State/Country:	JAPAN

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13611463

OP $40.00 13611463

CORRESPONDENCE DATA

Fax Number: 2125880500

Correspondence will be sent via US Mail when the fax attempt is unsuccessful.

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Email: SARJUNE@FLHLAW.COM
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ATTORNEY DOCKET NUMBER:	450100-06706
NAME OF SUBMITTER:	William S. Frommer

Total Attachments: 4
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source=01181804#page4.tif

Attorney Docket No. 450100-06706
SONY Ref. No.: SP326080US00

ASSIGNMENT

WHEREAS, I, as below named inventors, residing at the addresses stated next to our names, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in
INFORMATION PROCESSING METHOD, INFORMATION PROCESSING SYSTEM, INFORMATION PROCESSING APPARATUS, AND PROGRAM
for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address:

AND WHEREAS, **SONY CORPORATION, a Japanese corporation, with offices at 1-7-1 Konan, Minato-ku, Tokyo, Japan** (hereinafter referred to as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries:

NOW THEREFORE, in consideration of the sum of One Dollar ($1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense:

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: Serial Number: ______________________, Filing Date: ________________________________.

This assignment executed on the dates indicated below.

KYOSUKE YOSHIDA Name of first or sole inventor	 Execution date of U.S. Patent Application
KANAGAWA, JAPAN Residence of First or sole inventor	
x KYOSUKE YOSHIDA Signature of first or sole inventor	August 29, 2012 Date of this assignment
YOSHIHIRO TAMURA Name of second inventor	 Execution date of U.S. Patent Application
KANAGAWA, JAPAN Residence of second inventor	
Yoshihiro Tamura Signature of second inventor	August 31, 2012 Date of this assignment
ICHIRO OGATA Name of third inventor	 Execution date of U.S. Patent Application
KANAGAWA, JAPAN Residence of third inventor	
 Signature of third inventor	 Date of this assignment

ADDITIONAL INVENTOR(S)

YOSHINORI TAKAGI	
Name of fourth inventor	Execution date of U.S. Patent Application
KANAGAWA, JAPAN	
Residence of fourth inventor	
Yoshinori Takagi	Sep 3, 2012
Signature of fourth inventor	Date of this assignment
HIROFUMI HIBI	
Name of fifth inventor	Execution date of U.S. Patent Application
KANAGAWA, JAPAN	
Residence of fifth inventor	
Hirofumi Hibi	Sep 3, 2012
Signature of fifth inventor	Date of this assignment
DAISUKE IZAKI	
Name of sixth inventor	Execution date of U.S. Patent Application
TOKYO, JAPAN	
Residence of sixth inventor	
Daisuke Izaki	Sep, 6, 2012
Signature of sixth inventor	Date of this assignment
Name of seventh inventor	Execution date of U.S. Patent Application
Residence of seventh inventor	
Signature of seventh inventor	Date of this assignment
Name of eighth inventor	Execution date of U.S. Patent Application
Residence of eighth inventor	
Signature of eighth inventor	Date of this assignment
Name of ninth inventor	Execution date of U.S. Patent Application
Residence of ninth inventor	
Signature of ninth inventor	Date of this assignment

ASSIGNMENT

WHEREAS, I, as below named inventors, residing at the addresses stated next to our names, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in
INFORMATION PROCESSING METHOD, INFORMATION PROCESSING SYSTEM, INFORMATION PROCESSING APPARATUS, AND PROGRAM
for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, **SONY CORPORATION, a Japanese corporation, with offices at 1-7-1 Konan, Minato-ku, Tokyo, Japan** (hereinafter referred to as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar ($1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict wSetpith this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: Serial Number: 13/611,463, Filing Date: September 12, 2012.

This assignment executed on the dates indicated below.

KYOSUKE YOSHIDA Name of first or sole inventor	Execution date of U.S. Patent Application
KANAGAWA, JAPAN Residence of First or sole inventor	
Signature of first or sole inventor	Date of this assignment
YOSHIHIRO TAMURA Name of second inventor	Execution date of U.S. Patent Application
KANAGAWA, JAPAN Residence of second inventor	
Signature of second inventor	Date of this assignment
ICHIRO OGATA Name of third inventor	Execution date of U.S. Patent Application
KANAGAWA, JAPAN Residence of third inventor	
Ichiro Ogata Signature of third inventor	October 30, 2012 Date of this assignment

ADDITIONAL INVENTOR(S)

YOSHINORI TAKAGI
Name of fourth inventor

Execution date of U.S. Patent Application

KANAGAWA, JAPAN
Residence of fourth inventor

Signature of fourth inventor

Date of this assignment

HIROFUMI HIBI
Name of fifth inventor

Execution date of U.S. Patent Application

KANAGAWA, JAPAN
Residence of fifth inventor

Signature of fifth inventor

Date of this assignment

DAISUKE IZAKI
Name of sixth inventor

Execution date of U.S. Patent Application

TOKYO, JAPAN
Residence of sixth inventor

Signature of sixth inventor

Date of this assignment

Name of seventh inventor

Execution date of U.S. Patent Application

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Name of eighth inventor

Execution date of U.S. Patent Application

Residence of eighth inventor

Signature of eighth inventor

Date of this assignment

Name of ninth inventor

Execution date of U.S. Patent Application

Residence of ninth inventor

Signature of ninth inventor

Date of this assignment